



# PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Farnworth et al.

**Serial No.:** 10/666,930

**Filed:** September 19, 2003

**For: METHOD AND APPARATUS FOR SUPPORTING WAFERS FOR DIE SINGULATION AND SUBSEQUENT HANDLING**

**Examiner:** Unknown

**Group Art Unit: 2812**

**Attorney Docket No.: 2269-5529US**  
**(02-0766.00/US)**

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 5, 2004  
Date

Rachael M. Harris  
Signature

Rachael M. Harris  
Name (Type/Print)

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 or PTO/SB/08 be considered by the Examiner and made of record. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
6,251,488	06/26/01	Miller et al.
6,259,962	07/10/01	Gothait
6,268,584	07/31/01	Keicher et al.
6,391,251	05/21/02	Keicher et al.
6,562,661	05/13/03	Grigg

Other Documents

U.S. Patent Application Publication 2002/0171177 A1 to Kritchman et al., dated November 21, 2002

U.S. Patent Application Publication 2003/0151167 A1 to Kritchman et al., dated August 14, 2003

U.S. Patent Application Publication 2003/0176021 A1 to Grigg, dated September 18, 2003

MILLER et al., "Maskless Mesoscale Materials Deposition", Deposition Technology, September 2001, pages 20-22

MILLER, "New Laser-Directed Deposition Technology", Microelectronic Fabrication, August 2001, page 16

Webpage, Objet Prototyping the Future, "Objet FullCure700 Series", 1 page

Webpage, Objet Prototyping the Future, "How it Works", 2 pages

U.S. Patent Application No. 09/512,203, filed February 24, 2000, entitled "Tape Stiffener, Semiconductor Device Component Assemblies Including Same, and Stereolithographic Methods for Fabricating Same", inventor Ford B. Grigg

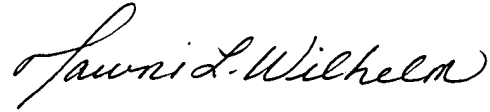
U.S. Patent Application No. 10/666,742, filed September 19, 2003, entitled "Support Structure for Thinning Semiconductor Substrates and Thinning Methods Employing the Support Structure", inventor Wood et al.

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

Serial No. 10/666,930

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

A handwritten signature in cursive script, reading "Tawni L. Wilhelm".

Tawni L. Wilhelm

Registration No. 47,456

Attorney for Applicant(s)

TRASKBRITT

P.O. Box 2550

Salt Lake City, Utah 84110-2550

Telephone: 801-532-1922

Date: January 5, 2004

TLW/sls:rmh

Enclosures: Form PTO-1449 or PTO/SB/08

Copy of documents cited

Document in ProLaw

**Burden Hour Statement:** This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



PTO/SB/08B(10-01)

Approved for use through 10/31/2002. OMB 0651-0031

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number

Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**

(use as many sheets as necessary)

Sheet 2 of 2

**Complete if Known**

Application Number	10/666,930
Filing Date	September 19, 2003
First Named Inventor	Farnworth et al.
Group Art Unit	2812
Examiner Name	Unknown
Attorney Docket Number	5529UIS (02-0766 00/UIS)

**OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS**

Examiner Initials *	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
		U.S. Patent Application Publication 2002/0171177 A1 to Kritchman et al., dated November 21, 2002	
		U.S. Patent Application Publication 2003/0151167 A1 to Kritchman et al., dated August 14, 2003	
		U.S. Patent Application Publication 2003/0176021 A1 to Grigg, dated September 18, 2003	
		MILLER et al., "Maskless Mesoscale Materials Deposition", Deposition Technology, September 2001, pages 20-22	
		MILLER, "New Laser-Directed Deposition Technology", Microelectronic Fabrication, August 2001, page 16	
		Webpage, Objet Prototyping the Future, "Objet FullCure700 Series", 1 page	
		Webpage, Objet Prototyping the Future, "How it Works", 2 pages	
		U.S. Patent Application No. 09/512,203, filed February 24, 2000, entitled "Tape Stiffener, Semiconductor Device Component Assemblies Including Same, and Stereolithographic Methods for Fabricating Same", inventor Ford B. Grigg	
		U.S. Patent Application No. 10/666,742, filed September 19, 2003, entitled "Support Structure for Thinning Semiconductor Substrates and Thinning Methods Employing the Support Structure", inventor Wood et al.	

Examiner Signature		Date Considered	
-----------------------	--	--------------------	--

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Unique citation designation number (optional). <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.